Preliminary

N-Channel Enhancement Mode Power MOSFET 500V / 75A

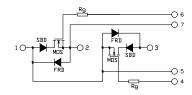
Features

- ♦ V_{DSS} = 500V
- ightharpoonup R_{DS(ON)} Typ.65mΩ@ V_{GS} = 10 V
- Fully Avalanche Rated
- Pb Free & RoHS Compliant
- Isolation Type Package
- Electrically Isolation base plate

Applications

- Backlighting
- **Power Converters**
- Synchronous Rectifiers

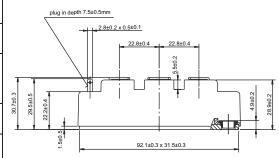


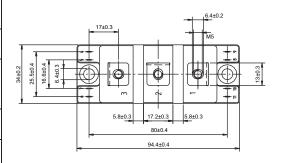


Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Parameter		Symbol	Ratings	Unit	
Drain-Source Voltage		V _{DS}	500	V	
Gate-Source Voltage		V _{GS}	±20	v	
Drain Current-Continuous	Duty=50%	- In	75	А	
	D.C.	ID	55		
Drain Current-Pulsed @ T _C =25°C Note1		I _{DM}	150	Α	
Maximum Power Dissipation		P _D	500	w	
Storage Temperature Range		T _{STG}	-50 to +125	°C	
Operating Junction Temperature Range		TJ	-50 to +150	°C	
Thermal Resistance, Junction-to-Case	MOSEET	$R heta_Jc$	0.25	°C/W	
	Diode	N/JC	2.00		
Isolation Voltage (A.C. 1 minute)		Viso	2500	V	
Mounting torque (M5 Screw)		M d	3-5	Nm	
Weight			142	g	

Package Outlines





Dimensions in mm (1 mm = 0.0394")

■ Electrical Characteristics @ T_J =25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
OFF Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V · I _{DS} =3mA	500	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} =0V , V _{DS} =500V	-	-	1	mA
Gate-Body Leakage	I _{GSS}	V _{GS} =±20V , V _{DS} =0V	-		10	μ A
ON Characteristics						
Gate Threshold Voltage	V _{TH}	V _{DS} =V _{GS} , I _{DS} =5mA	2	2.9	4	٧
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V , I _{DS} =35A	-	65	75	mΩ
Forward Transconductance	g _{fs}	V _{DS} =15V, I _{DS} =35A	-	75	-	s
Dynamic Characteristics			•			
Input Capacitance	C _{iss}	V _{DS} =25V	-	12	-	
Output Capacitance	Coss	V _{GS} =0V	-	0.7	-	nF
Reverse Transfer Capacitance	C _{rss}	Freq.=1MHz	-	0.5	-	
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}		-	82	-	- ns
Rise Time	t _r	V _{Dd} =1/2V _{DSS}	-	120	-	
Turn-Off Delay Time	t _{d(off)}	V _{GS} =-5V,+10V	-	330	-	
Fall Time	t _f	I _{DS} =35A	-	35	-	
Diode Forward Voltage	E _(on)	$R_G=2\Omega$	-	0.2	-	mJ
Diode Continuous Forward Current	E _(off)		-	2.9	-	IIIJ

■ Reverse Diode Characteristics (TJ = 25°C)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Peak Forward Voltage	VF	I⊧=75A,T」=25°C	-	1.8	-	٧
Diode Pulsed Current Note1	I F,pulse		-	-	150	Α
Peak Reverse Recovery Current	IRM	I _F =75A -dis/dt=100A/ μ s	-	16	-	Α
Recovered Charge	Qrr	I _F =75A -dis/dt=100A/ μ s	-	0.53	-	μα
Reverse Recovery Energy	Erec	I _F =75A -dis/dt=100A/ μ s	-	0.218	-	mJ
Reverse Recovery Time	Trr	I _F =75A -dis/dt=100A/ // s	-	53	-	ns

Notes:

^{1.} Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle > 2%.

Typical Characteristics

Fig. 1 Typical Output Characteristics

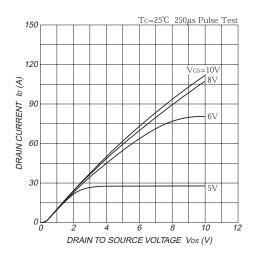


Fig. 3 Typical Drain-Source On Voltage Vs. Junction Temperature

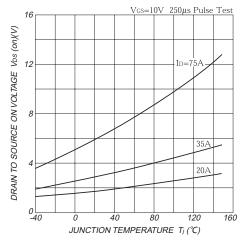


Fig. 5 Typical Gate Charge Vs. Gate-Source Voltage

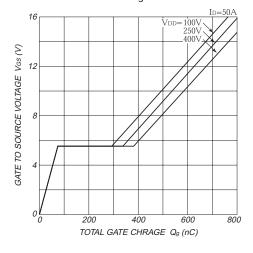


Fig. 2 Typical Drain-Source On-Voltage Vs. Gate-Source Voltage

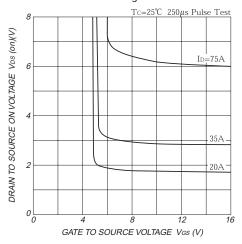


Fig. 4 Typical Capacitance Vs. Drain-Source Voltage

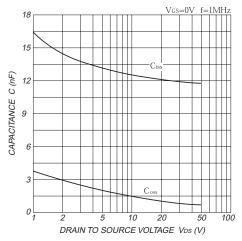
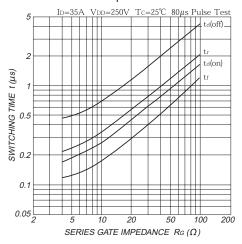


Fig. 6 Typical Switching Time Vs. Series Gate impedance



Typical Characteristics

Fig. 7 Typical Switching Time Vs. Drain Current

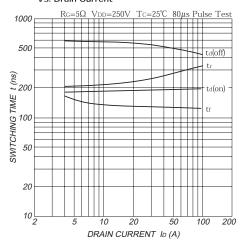


Fig. 9 Typical Reverse Recovery Characteristics

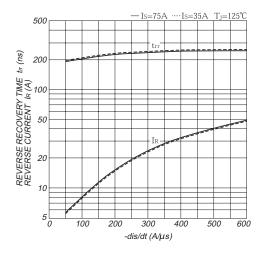


Fig. 11-1 Normalized Transient Thermal impedance(MOSFET)

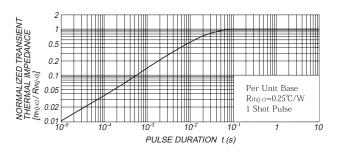


Fig. 8 Typical Source-Drain Diode Forward Characteristics

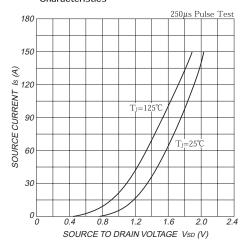


Fig. 10 Maximum Safe Operating Area

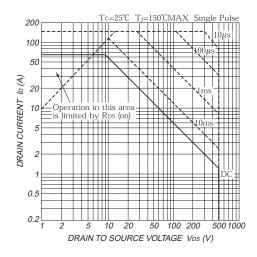
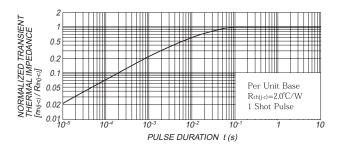


Fig. 11-2 Normalized Transient Thermal impedance(DIODE)





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